
BioSLIP® 222
Micronized Bio-based Wax Alloy






Product Description:

BioSLIP® 222 is a micronized bio-based wax alloy that provides excellent lubricity and wear resistance.





Application:

BioSLIP® 222 is recommended for all clear OPV, water-based, solvent-based, and UV inks and coatings at 1-3% of the total formula weight. BioSLIP® 222 also shows exceptional performance in can coating especially for slip and scratch resistance with minimal impact on gloss and clarity.

Features and Benefits:

-  Slip
-  Mar/Scratch Resistance
-  Gloss Retention
-  Superior Clarity
-  Enhanced mobility

Typical Properties:

 Particle Size Mean Value:	5 µm
 NPIRI Grind:	2.5 Max
 Hegman Grind:	6.5 Min
 DSC Melt Point:	102-106°C

Regulatory Status:

The components of this product are listed on multiple chemical inventories. For specific information on the applicable chemical inventories, please refer to the product SDS.

Safety, Shipping and Handling:

For complete safety, shipping and handling information please contact your regional Customer Service Representative, or our Customer Service Team at customerserviceteam@shamrocktechnologies.com.

For **more** information about Shamrock's other products or capabilities please visit us at our website, ShamrockTechnologies.com.

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